# Supplier Name: Te Contact Info: ti. Form/Declaration Type: Di Created on: Declaration

#### Texas Instruments Inc. (DUNS# 00-732-1904) ti.com/support

Distribute - RoHS and IEC 62474 DB 06/14/2022

# Details for "TLV7112525DSER"

**Current Product Information** 

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package   Pins	Package body size (mm)	Total device mass (mg)*
TLV7112525DSER	NIPDAUAG	Level-1-260C-UNLIM	Ext-Mfg	DSE   6	1.5x1.5x0.75	3.4

\*Total Device Mass

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value

## **Environmental Ratings Information**

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

## **Component Information**

				Homogeneous Material Level		Component Level	
Component	Substance	CAS Number	Amount (mg)	Percentage %	ppm	Percentage %	ppm
Bond Wire							
Copper and Its Alloys	Copper	7440-50-8	0.010727	97.669125	976691	0.31341	3134
Precious Metals	Palladium	7440-05-3	0.000256	2.330875	23309	0.00748	75
Sub-Total			0.010983	100	1000000	0.32089	3209
Die Attach Adhesive	•	-			•		
Other Inorganic Materials	Aluminum Oxide	1344-28-1	0.022119	30	300000	0.64625	6463
Other Inorganic Materials	Silica	7631-86-9	0.003318	4.500203	45002	0.096942	969
Thermoplastics	Ероху	85954-11-6	0.048293	65.499797	654998	1.410975	14110
Sub-Total			0.07373	100	1000000	2.154167	21542
Lead Frame	•	-			•		
Copper and Its Alloys	Copper	7440-50-8	0.876994	97.443778	974438	25.62311	256231
Copper and Its Alloys	Iron	7439-89-6	0.021145	2.349444	23494	0.617793	6178
Copper and Its Alloys	Phosphorus	7723-14-0	0.000739	0.082111	821	0.021591	216
Zinc and Its Alloys	Zinc	7440-66-6	0.001122	0.124667	1247	0.032781	328
Sub-Total			0.9	100	1000000	26.295276	262953
Lead Frame Plating	•	-			•		
Nickel and Its Alloys	Nickel	7440-02-0	0.00973	97.3	973000	0.284281	2843
Precious Metals	Gold	7440-57-5	0.00003	0.3	3000	0.000877	9
Precious Metals	Palladium	7440-05-3	0.00021	2.1	21000	0.006136	61
Precious Metals	Silver	7440-22-4	0.00003	0.3	3000	0.000877	9
Sub-Total			0.01	100	1000000	0.29217	2922
Mold Compound	•	-			•		
Other Inorganic Materials	Fused Silica	60676-86-0	1.765148	90.49999	905000	51.572282	515723
Other Plastics and Rubber	Carbon Black	1333-86-4	0.009752	0.49999	5000	0.284924	2849
Thermoplastics	Epoxy	85954-11-6	0.17554	9.000021	90000	5.128748	51287
Sub-Total			1.95044	100	1000000	56.985954	569860
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	0.477515	100	1000000	13.951543	139515
Sub-Total			0.477515	100	1000000	13.951543	139515
Total			3.422668			100	1000000

#### Important Note

The ppm calculations are at the homogeneous material level and are maximum concentration values. The ppm displayed represents the homogeneous material with the highest ppm

for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.

The ppm calculations are at the component level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the component.

See Glossary of Terms for more details.

### Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSIs or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

# Product Content Methodology

#### For an explanation of the methods used to determine material weights, See Product Content Methodology

#### Material Declaration Certificate for Semiconductor IC Packaged Products

T certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

#### Important Information/Disclaimer

Th bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. The may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. The material content information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

For additional information, please contact TI customer support.

#### Signature: (click here for a fuller statement with a signed certificate)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality For further environmental statements, please go to www.ti.com/ecoinfo Created on: 06/14/2022

RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Po-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in http://www.ti.com/lit/pdf/szzq088

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb203) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.